优尚

YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D $T_C = +25°C$
-12V	6mΩ @ $V_{GS} = -4.5V$	-80A
	8mΩ @ $V_{GS} = -2.5V$	-70A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Notebook Battery Power Management
- DC-DC Converters
- Load Switch

Features

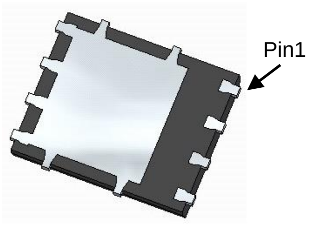
- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching – Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low $R_{DS(ON)}$ – Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed

Mechanical Data

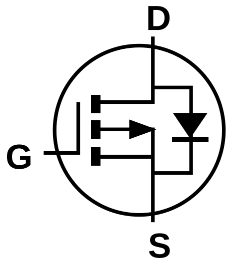
- Case: PowerDI®5060-8
- Case Material: Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 ⓔ3
- Weight: 0.097 grams (Approximate)

PowerDI5060-8

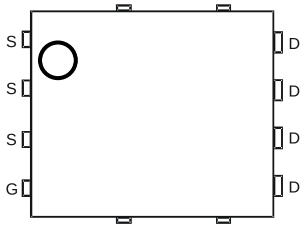
Top View



Bottom View



Internal Schematic



Top View
Pin Configuration

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-12	V
Gate-Source Voltage		V_{GSS}	±8	V
Continuous Drain Current (Note 7) V_{GS} = -4.5V	T_C = +25°C	I_D	-80	A
	T_C = +100°C		-60	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I_{DM}	-140	A
Maximum Continuous Body Diode Forward Current (Note 6)		I_S	-3.6	A
Avalanche Current, L=0.1mH (Note 8)		I_{AS}	-18	A
Avalanche Energy, L=0.1mH (Note 8)		E_{AS}	-17	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	1.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	86	°C/W
	t<10s		74	
Total Power Dissipation (Note 6)		P_D	3.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	47	°C/W
	t<10s		40	
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	1.0	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1	µA	V_{DS} = -12V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.4	—	-1	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	4	6	mΩ	V_{GS} = -4.5V, I_D = -15A
		—	5	8		V_{GS} = -2.5V, I_D = -10A
Diode Forward Voltage	V_{SD}	—	-0.7	-1.1	V	V_{GS} = 0V, I_S = -1A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	6,334	—	pF	V_{DS} = -10V, V_{GS} = 0V f = 1MHz
Output Capacitance	C_{oss}	—	1094	—		
Reverse Transfer Capacitance	C_{rss}	—	895	—		
Gate Resistance	R_g	—	3.5	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = -8V)	Q_g	—	124	—	nC	V_{DD} = -10V, I_D = -20A
Total Gate Charge (V_{GS} = -4.5V)	Q_g	—	72	—		
Gate-Source Charge	Q_{gs}	—	9	—		
Gate-Drain Charge	Q_{gd}	—	17	—		
Turn-On Delay Time	$t_{D(ON)}$	—	11	—	ns	V_{GS} = -4.5V, V_{DD} = -10V, R_g = 1Ω, I_D = -10A
Turn-On Rise Time	t_R	—	21	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	105	—		
Turn-Off Fall Time	t_F	—	94	—		
Reverse Recovery Time	t_{RR}	—	27	—	ns	I_F = -10A, di/dt = -100A/µs
Reverse Recovery Charge	Q_{RR}	—	10	—	nC	I_F = -10A, di/dt = -100A/µs

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).
8. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
9. Short duration pulse test used to minimize self-heating effect.
10. Guaranteed by design. Not subject to product testing.

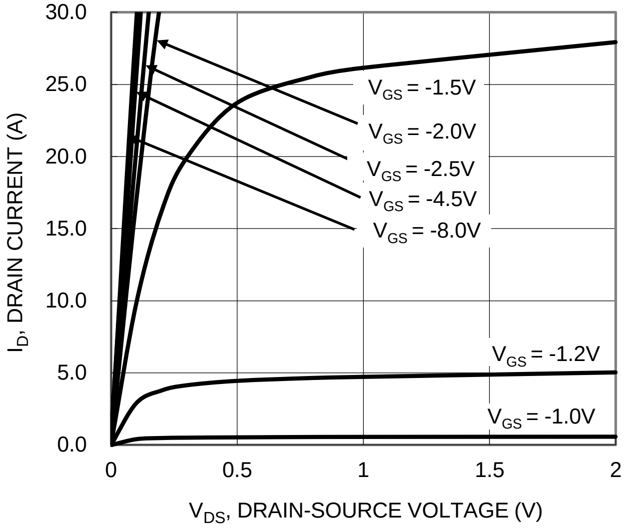


Figure 1. Typical Output Characteristic

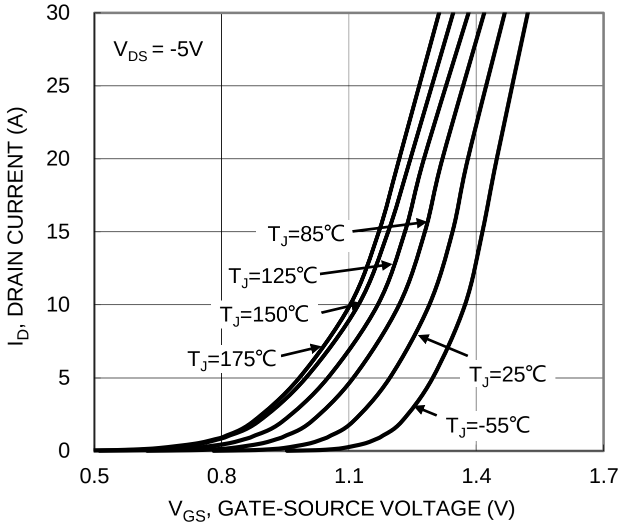


Figure 2. Typical Transfer Characteristic

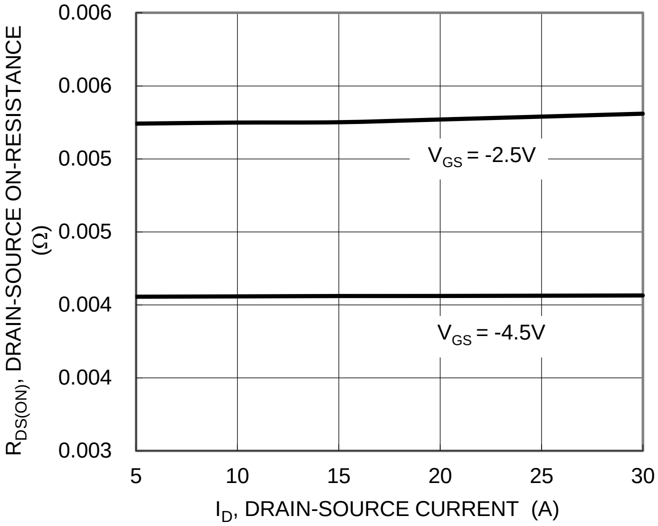


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

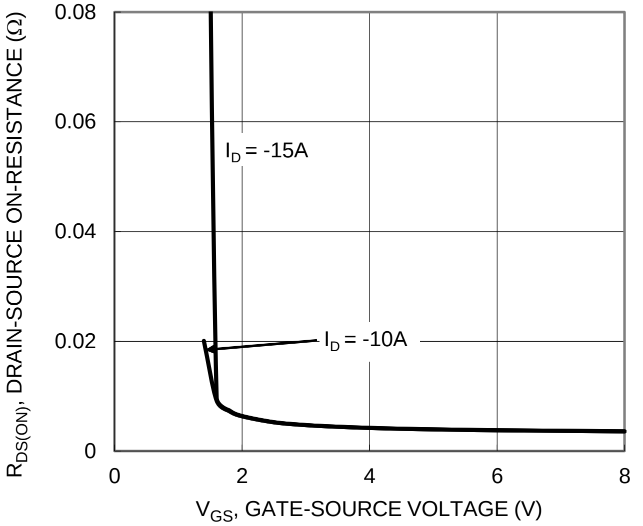


Figure 4. Typical Transfer Characteristic

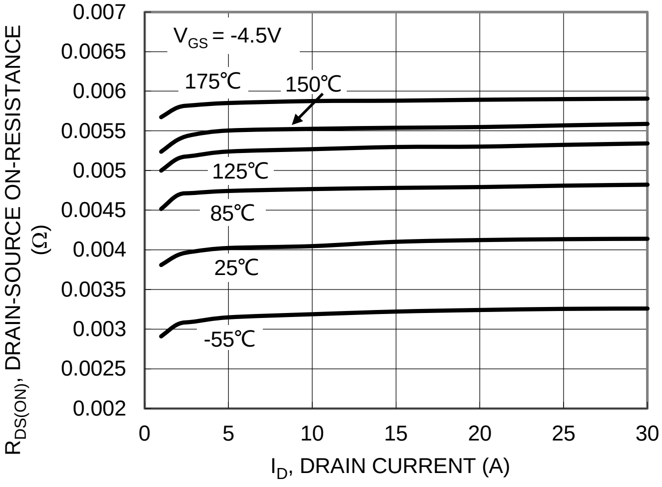


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

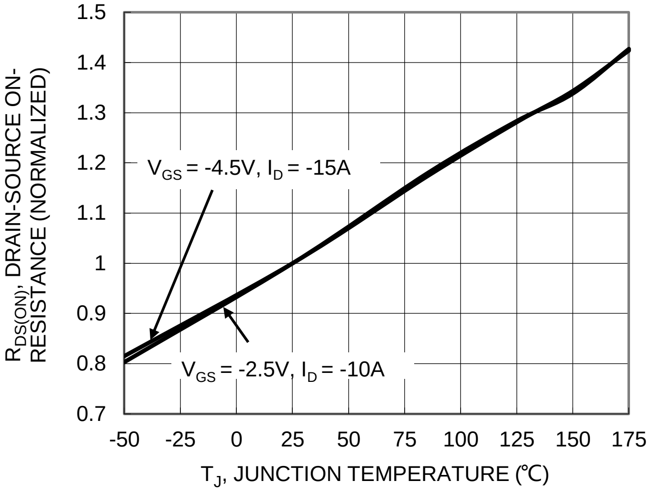


Figure 6. On-Resistance Variation with Temperature

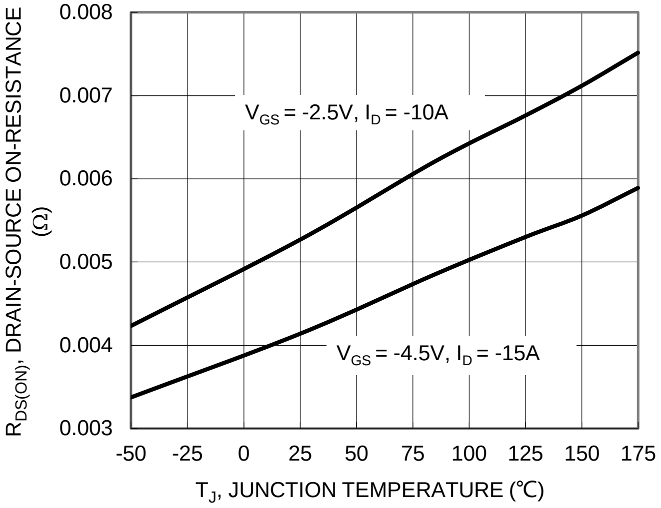


Figure 7. On-Resistance Variation with Temperature

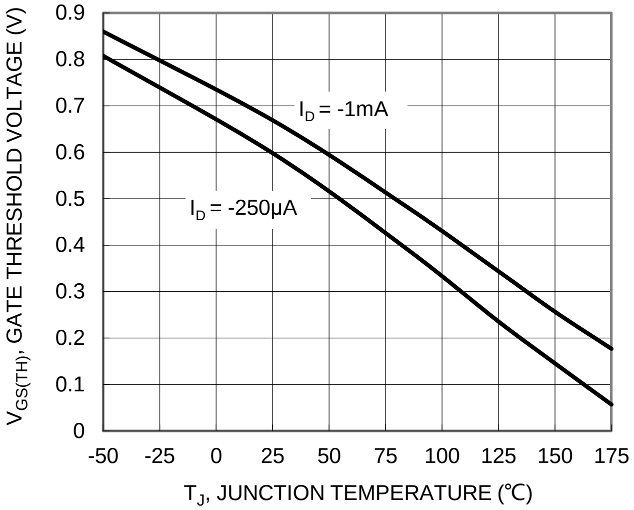


Figure 8. Gate Threshold Variation vs. Junction Temperature

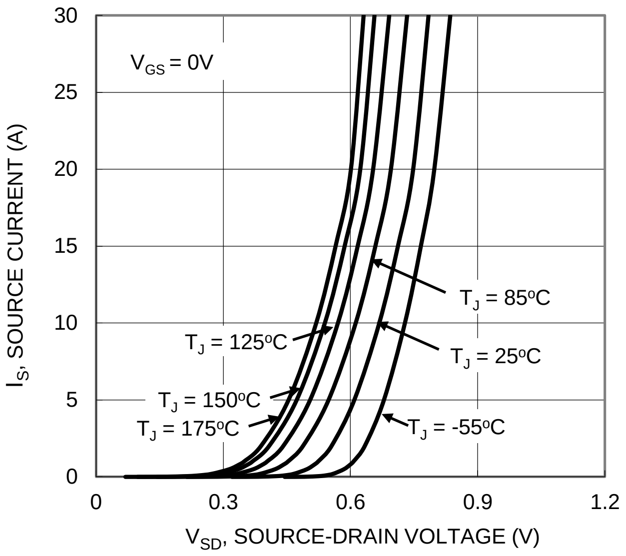


Figure 9. Diode Forward Voltage vs. Current

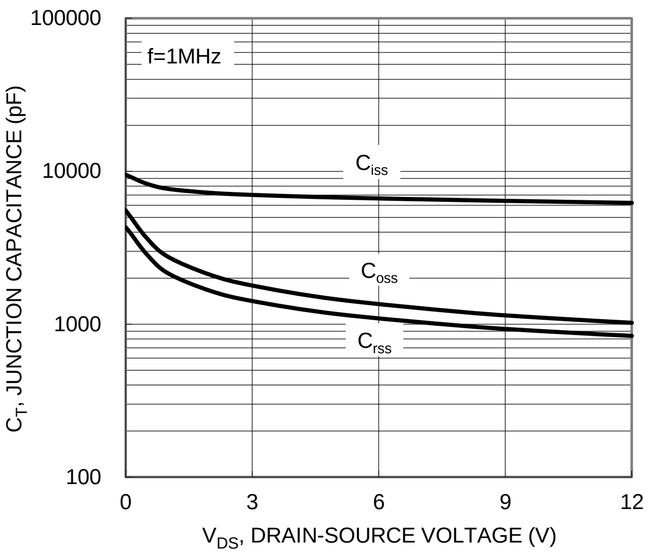


Figure 10. Typical Junction Capacitance

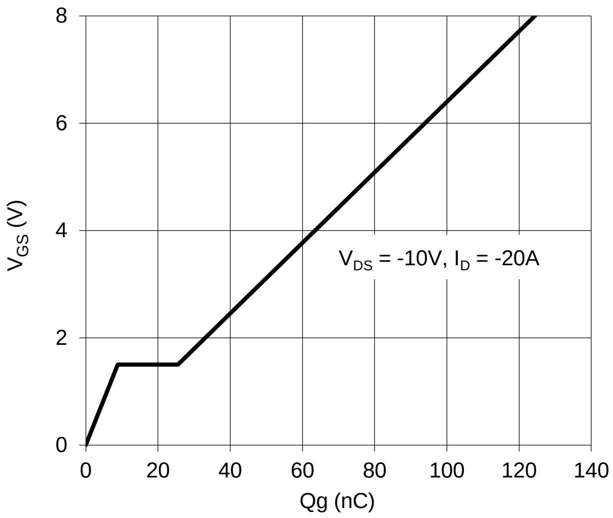


Figure 11. Gate Charge

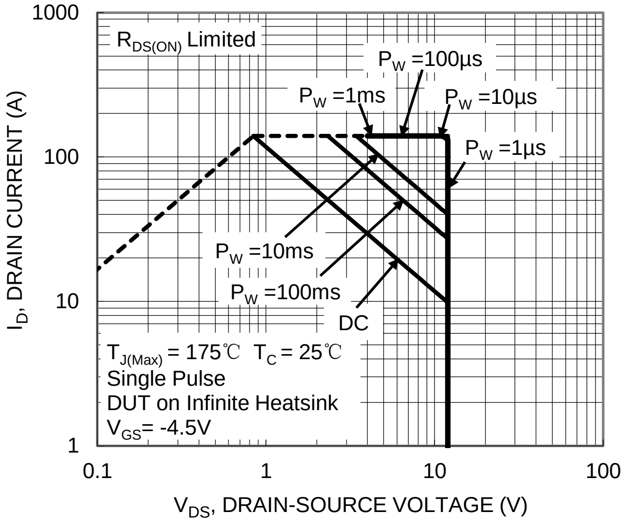


Figure 12. SOA, Safe Operation Area

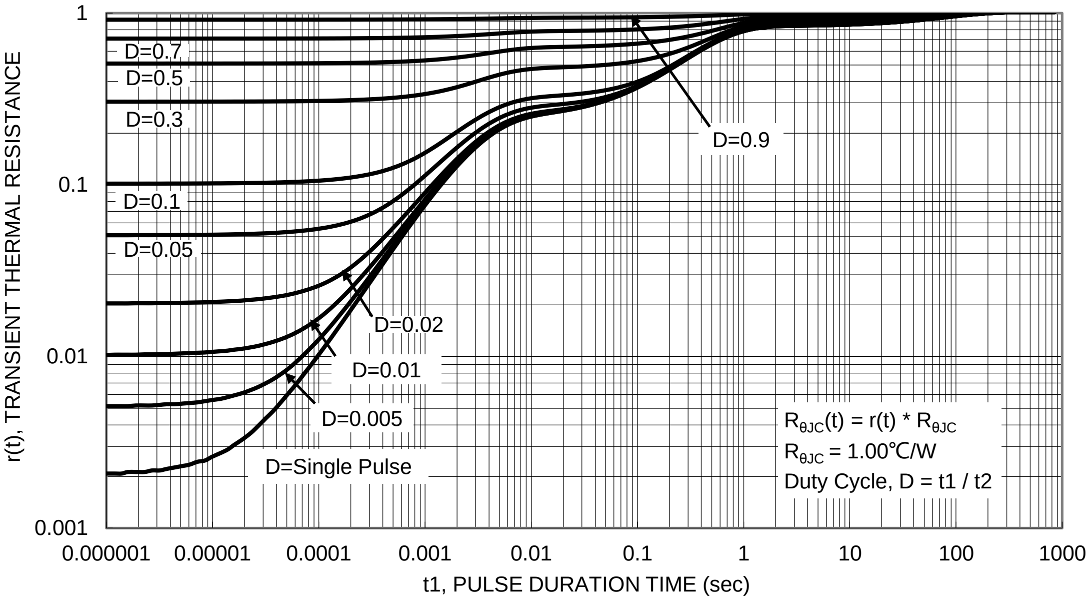
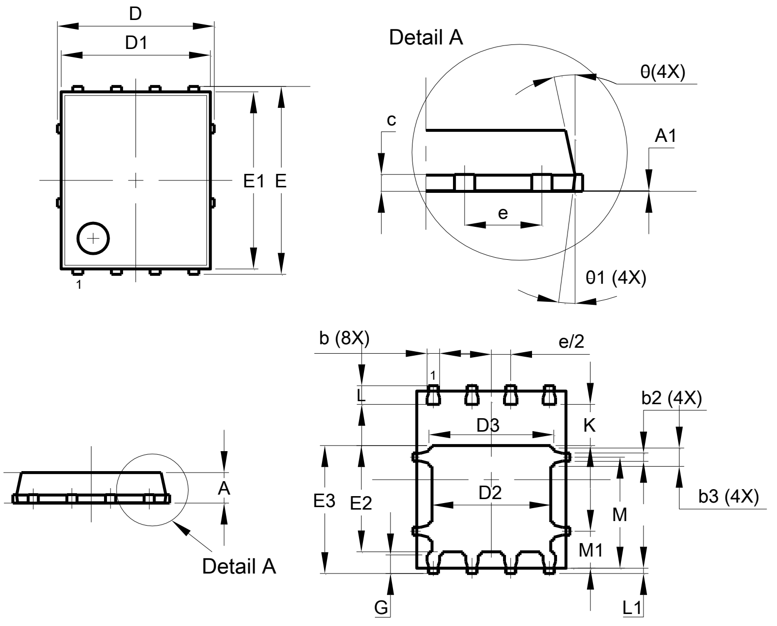


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

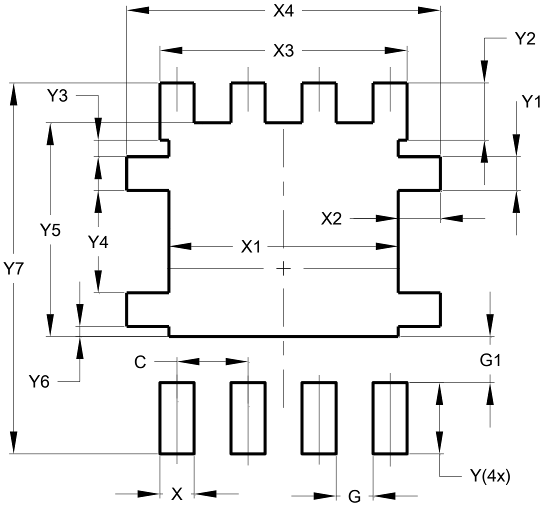
PowerDI5060-8



PowerDI5060-8			
Dim	**Min**	**Max**	**Typ**
A	0.90	1.10	1.00
A1	0.00	0.05	–
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	–	–
L	0.51	0.71	0.61
L1	0.100	0.200	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
Θ	10º	12º	11º
Θ1	6º	8º	7º
All Dimensions in mm			

Suggested Pad Layout

PowerDI5060-8



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610